SINGLE SIDE WORKPIECE PROCESSING

Abstract

A centrifugal workpiece processor for processing semiconductor workpieces includes a head which holds and spins the workpiece. The head includes a rotor having a gas system. Gas is sprayed from inlets in the rotor to create a rotational gas flow. The rotational gas flow causes pressure conditions which hold the edges of a first side of the workpiece against contact surfaces on the rotor. The rotor and the workpiece rotate together. Guide pins adjacent to a perimeter help align the workpiece with the rotor. An angled surface helps deflect spent process liquid away from the workpiece. The head is moveable into multiple different engagement positions with a bowl. Spray nozzles in the bowl spray a process liquid onto the second side of the workpiece, as the workpiece is spinning, to process the workpiece. A moving end point detector may be used to detect an end point of processing.

Figure: 5